

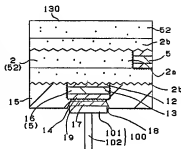
(19) **KOREAN INTELLECTUAL PROPERTY OFFICE****KOREAN PATENT ABSTRACTS**

(11)Publication number: **1020010093184 A**
 (43)Date of publication of application: **27.10.2001**

(21)Application number: **1020017007575** (71)Applicant: **IBIDEN CO., LTD.**
 (22)Date of filing: **16.06.2001** (72)Inventor: **HIROSE NAOHIRO
ITO HITOSHI
IWATA YOSHIYUKI
KAWADE MASANORI
YAZU HAJIME**
 (30)Priority: **..**
 (51)Int. Cl: **H05K 3/46**

(54) CONDUCTIVE CONNECTING PIN AND PACKAGE BOARD**(57) Abstract:**

On the board provided with a conductive layer (5), a pad (16) is formed to fix a conductive connecting pin (100) on a package board (310). The conduction connecting pin (100) serves as electrical connection to a motherboard. The pad (16) is coated with an organic-resin insulating layer (15) having an opening section (18) from which the pad (16) is partially exposed. The conductive connecting pin (100) is fixed to the pad exposed from the opening section using a conductive adhesive (17), preventing the conductive connecting pin (100) from separating off the board at the time of mounting.



copyright KIPO & WIPO 2007

Legal Status

Date of request for an examination (20041026)

Notification date of refusal decision (00000000)

Final disposal of an application (registration)

Date of final disposal of an application (20081128)

Patent registration number (1008821730000)

Date of registration (20090130)

Number of opposition against the grant of a patent ()

Date of opposition against the grant of a patent (00000000)

Number of trial against decision to refuse ()

Date of requesting trial against decision to refuse ()

Date of extinction of right ()